■Automatic dimension measuring mode

1)This control unit measures wafer thickness before and during grinding with two probes, displays the measurement results on the opreration panel, and generates control signals on real time basis.

2)Wafer dimension measuring mode	Two-point in-process gauge
3)Wafer dimension setting mode	LCD Touch panel
4)Wafer dimension display range	0 to 1400 um
5)Wafer dimension minimum setting range	0.1um

■Wafer, Chuck table

1)Material	Porous ceramic
2) Rotation speed	1 to 600 rpm
3) Bearing	Mechanical bearing Air bearing (optional)
4) Number of tables	3 tables
5) Chuck method	Vacuum chucking
6) Cleaning method	Water + ceramic ring
7) Wafer size	5, 6 and 8 inch supported (and optionally 4 inch)

■Wafer cleaning unit

1)DI water and brush(grinding side)

2)DI water and air blow and spin(grinding side)

■Auto loading and unloading

1)Number bof cassettes	2 cassettes
2)Cassette	A : Carrying to slot of loading cassette B : One loading- and one unloading-
3)Wafer handling system	Robot

■Operation panel

1)Display	13.3" LCD touch panel
2)Main control panel	13.3" LCD touch panell
3)Sub control panel	Hand panel